

Contents

Preface xv

1	Overview of Flexible Electronic Encapsulating Technology	1
	<i>Zhenguo Liu and Yongji Chen</i>	
1.1	Flexible Electronics Overview	1
1.2	Development of Flexible Electronic Encapsulating Technology	5
1.2.1	Flip Chip Process	11
1.2.2	Progress of CIF-Based Flexible Electronic Encapsulating Technology	13
1.3	Encapsulating Technology of Several Important Flexible Electronic Devices	14
1.3.1	Organic Light-Emitting Diode	14
1.3.2	Flexible Solar Cell Encapsulating	21
1.3.3	Flexible Amorphous Silicon Solar Cells	21
1.3.4	Flexible Perovskite Solar Cells	23
1.4	Flexible Electronic Encapsulating Materials	26
1.4.1	Selection Principle of Flexible Electronic Encapsulating Materials	26
1.4.2	Desirable Properties of Flexible Electronic Encapsulating Materials	27
1.5	Overview of the Development of Flexible Electronic Packaging at Home and Abroad	28
	References	29
2	Basic Concepts Related to Flexible Electronic Packaging	33
	<i>Peng-an Zong and Mengran Chen</i>	
2.1	Composition of Flexible Electronic Packaging	33
2.1.1	Flexible Substrate	34
2.1.2	Electronic Components	35
2.1.3	Crosslinked Conductive Materials	36
2.1.4	Adhesive Layer	36
2.1.5	Coating Layer	37
2.2	Flexible Electronic Packaging Structure	37
2.2.1	Curved Structures of Hard Thin Films	38
2.2.2	Island-Bridge Structure	39

2.2.3	Pre-strained Super-Soft Interconnect Structure	40
2.2.4	Open Grid Structure	40
2.3	Encapsulation Principle	41
2.3.1	Basic Principle of Penetration	41
2.3.2	Permeation Mechanism of Water Vapor and Gas	43
2.3.3	Barrier Performance Measurement	47
2.3.4	Thin-Film Barrier Technology for Organic Devices	49
2.3.4.1	Single-Layer Film Package	50
2.3.4.2	Multilayer Film Packaging	53
2.3.5	Film Encapsulation Mechanics	58
2.4	Packaging Technology	62
2.4.1	Local Multilayer Packaging	62
2.4.2	Multilayer Barrier Film Packaging	62
2.4.3	Online Thin-Film Encapsulation	63
2.4.4	Atomic Layer Deposition (ALD) Encapsulation	63
2.4.5	Inkjet Packaging	64
2.4.6	Flexible Glass Packaging	65
2.5	Packaging Stability	65
2.6	Encapsulated Products	67
2.7	Chapter Summary	69
	References	69

3 Flexible Substrates 77

Yanhui Chen, Xian Zhang, and Zhiqiang Wu

3.1	Concept and Connotation of Flexible Substrates	77
3.2	Development History of Flexible Substrates	78
3.3	Flexible Substrate Materials	82
3.3.1	Polydimethylsiloxane	82
3.3.2	Polyvinyl Alcohol	82
3.3.3	Polycarbonate	84
3.3.4	Polyester	85
3.3.5	Polyimide	88
3.3.6	Polyurethane	89
3.3.7	Parylene	91
3.3.8	Liquid Crystal Polymer	92
3.3.9	Hydrogel	93
3.4	Molding Technology of Flexible Substrate	94
3.4.1	Coating Technology	94
3.4.1.1	Dip Coating Method	94
3.4.1.2	Air Knife Coating Method	95
3.4.1.3	Scraper Coating Method	96
3.4.1.4	Rotary Coating Method	96
3.4.2	Melt Extrusion Molding	96
3.4.3	Melt Extrusion Blow Molding	96
3.4.4	Solution Tape Casting	98

3.4.5	Bidirectional Drawing Molding	98
3.4.6	Chemical Vapor Deposition	99
3.5	Performance Evaluation of Flexible Substrates	101
3.5.1	Mechanical Flexibility	101
3.5.2	Ductility	102
3.5.3	Adhesive Property	103
3.5.4	Barrier Property	103
3.5.5	Electrical Property	105
3.5.6	Chemical Stability	105
3.5.7	Dimensional Stability	105
3.5.8	Surface Smoothness and Thickness Uniformity	106
3.5.9	Optical Clarity (Transmittance)	106
3.5.10	Biocompatibility	107
3.5.11	Bioabsorbability	107
3.6	Application of Flexible Substrates	108
3.6.1	Flexible Display Substrates	108
3.6.2	Flexible Electrode Substrates	109
3.6.3	Flexible Sensing Substrates	110
3.7	Development Trend of Flexible Substrates	111
3.7.1	Intelligent and Functional Flexible Substrates	111
3.7.2	Green Degradable Flexible Substrates	112
3.7.3	Optimization of Interface Compatibility of Flexible Substrates	113
	References	114
4	Test Methods	123
	<i>Junjie Yuan</i>	
4.1	Sealing Test	123
4.1.1	Direct Diffusion Method	124
4.1.1.1	Weight Cup Test	124
4.1.1.2	Differential Pressure Method	124
4.1.1.3	Balancing Method	124
4.1.1.4	Tunable Diode Laser Absorption Spectrometry	125
4.1.1.5	Isotope Labeling Mass Spectrometry	126
4.1.2	Indirect Optical Method	128
4.1.3	Indirect Electrical Method	129
4.1.3.1	Calcium Electrical Test	129
4.1.3.2	Dielectric Measurement Method	132
4.1.4	Indirect Electrochemical Method	133
4.1.4.1	Electrochemical Impedance Spectroscopy (EIS)	134
4.1.4.2	Leakage Current Monitoring Method (LCM)	134
4.1.4.3	Linear Scanning Voltammetry (LSV)	135
4.1.5	Indirect Electromechanical Method	136
4.2	Bending Test	136
4.2.1	Static Bending and Dynamic Bending	137
4.2.2	Three-Point Bending and Four-Point Bending	138

4.2.3	Push Bending and Roll Bending	140
4.2.3.1	Push Bending	140
4.2.3.2	Rolling Bend	141
4.3	Mechanical Performance Testing	143
4.4	Stability Testing	147
	References	149
5	Flexible Electronic Encapsulation	157
	<i>Tao Yu</i>	
5.1	Inorganic Encapsulating Material	158
5.1.1	Metal Encapsulating Material	158
5.1.1.1	Copper, Aluminum	158
5.1.1.2	Favorable Alloys	160
5.1.1.3	Copper–Tungsten Alloy (Cu–W)	160
5.1.2	Ceramic Encapsulating Material	161
5.1.2.1	Al ₂ O ₃ Ceramic Encapsulation Material	161
5.1.2.2	AlN Ceramic Encapsulation Materials	161
5.1.2.3	BeO Ceramic Encapsulation Material	161
5.1.2.4	BN Ceramic Encapsulation Materials	161
5.1.3	New Trend in Inorganic Encapsulating Materials Combined with Flexible Electronic Technology	162
5.2	Organic Encapsulating Material	164
5.2.1	Polymer Encapsulating Material	164
5.2.1.1	Epoxy Resins	165
5.2.1.2	Polyimide Resins	165
5.2.1.3	Organic Silicon	166
5.2.1.4	Bismaleimide	167
5.2.1.5	Bismaleimide Triazine Resin	168
5.2.2	Development Trend of Organic Encapsulating Materials in Flexible Electronic Devices	169
5.3	Organic–Inorganic Hybrid Encapsulating Material	170
5.3.1	Application of Organic–Inorganic Hybrid Materials in Flexible Electronics	170
5.3.1.1	Strain and Pressure Sensors	171
5.3.1.2	Temperature Sensor	172
5.3.1.3	Humidity Sensor	173
5.3.1.4	Optical Sensors	173
5.3.1.5	Other Types of Sensing Devices	174
5.3.2	Development Trends of Organic–Inorganic Hybrid Materials	174
	References	175
6	Development of Flexible Electronics Packaging Technology	179
	<i>Qiusi Rao</i>	
6.1	Flexible Electronics Packaging	179
6.1.1	Single-Layer Thin-Film Packaging	179

6.1.2	Multi-Layer Thin-Film Packaging	180
6.1.2.1	Barix Multilayer Thin-Film Packaging	180
6.1.2.2	Other Multilayer Thin-Film Packaging	182
6.2	Thin-Film Packaging Technology	183
6.2.1	PECVD Atomic Layer Deposition Packaging Technology	183
6.2.1.1	Introduction to PECVD Technology	183
6.2.1.2	Development of PECVD Technology	184
6.2.2	ALD Atomic Layer Deposition Packaging Technology	185
6.2.2.1	Introduction to ALD Technology	185
6.2.2.2	Development of ALD Technology	186
6.2.3	Inkjet Packaging Technology	189
6.2.3.1	Introduction to Inkjet Encapsulation Technology	189
6.2.3.2	Continuous Inkjet Printing	189
6.2.3.3	Drop-on-Demand Inkjet Printing	190
6.2.3.4	Development of Inkjet Printing Technology	191
	References	192
7	Application of Flexible Electronics Packaging	195
	<i>Yuezhou Zhang</i>	
7.1	Industry Chain Analysis of Flexible Electronics Packaging	195
7.1.1	Upstream, Midstream, and Downstream of the Flexible Electronics Industry Chain	195
7.1.2	Overview of the Development of Flexible Packaging Materials	196
7.2	Packaging Applications of Flexible OLED Devices	197
7.2.1	Stability Issues of Flexible OLED Devices	198
7.2.2	Flexible OLED Packaging Technology	201
7.2.2.1	Lack of Breakthrough in Encapsulating Technology	202
7.2.2.2	Low Yield Rate	203
7.3	Packaging Applications for Flexible Solar Cells	208
7.3.1	Inorganic Flexible Solar Cells	209
7.3.2	Organic Flexible Solar Cells	211
7.3.3	Dye-Sensitized Solar Cells	213
7.3.3.1	Structure of Dye-Sensitized Solar Cells	213
7.3.3.2	Light Anode	215
7.3.3.3	Counter Electrode	216
7.4	Packaging Applications for Flexible Electronic Devices	217
7.4.1	Basic Structure of Flexible Electronic Devices	217
7.4.2	Application of Flexible Electronic Devices	218
7.4.2.1	Optoelectronics	219
7.4.2.2	Robot	220
7.4.2.3	Biomedical	221
7.4.2.4	Energy Equipment	223
7.5	Packaging Applications for Flexible Electronics Sensors	226
7.5.1	Common Materials of Flexible Sensors	228
7.5.1.1	Flexible Substrate	228

7.5.1.2	Metal Materials	228
7.5.1.3	Inorganic Semiconductor Materials	229
7.5.1.4	Organic Materials	229
7.5.1.5	Carbon Materials	230
7.5.2	Flexible Gas Sensors	230
7.5.3	Flexible Pressure Sensors	230
7.5.4	Flexible Humidity Sensor	232
7.5.5	Normal Sensors Compare with Flexible Sensors	232
	References	233
8	Testing Standards	239
	<i>Junjie Yuan</i>	
8.1	Terminology and Alphabetic Symbols	240
8.1.1	Scope	240
8.1.2	Terms and Definitions	240
8.1.2.1	Terminology Classification	240
8.1.2.2	General Terms	240
8.1.2.3	Physical Characteristics Related Terms	240
8.1.2.4	Terms Related to Construction Elements	241
8.1.2.5	Symbols Related to Performances and Specifications	241
8.1.2.6	Terms Related to the Production Process	242
8.1.3	Alphabetic Symbols (Quantity Symbols/Unit Symbols)	242
8.1.3.1	Classification	242
8.1.3.2	Symbols	242
8.2	Mechanical Test Method (Deformation Test)	242
8.2.1	Cyclic Bending Test	243
8.2.1.1	Purpose	243
8.2.1.2	Testing Device	243
8.2.1.3	Test Procedure	245
8.2.1.4	Test Conditions and Reports	245
8.2.2	Static Bending Test	246
8.2.2.1	Purpose	246
8.2.2.2	Testing Device	246
8.2.2.3	Test Steps	247
8.2.2.4	Test Conditions and Reports	247
8.2.3	Combined Bending Test	247
8.2.3.1	Purpose	248
8.2.3.2	Testing Device	248
8.2.3.3	Test Procedure	248
8.2.3.4	Test Conditions and Reports	249
8.2.4	Rolling Test	250
8.2.4.1	Purpose	250
8.2.4.2	Testing Device	250
8.2.4.3	Test Procedure	250
8.2.4.4	Test Conditions and Reports	251

8.2.5	Static Rolling Test	251
8.2.5.1	Purpose	251
8.2.5.2	Testing Device	251
8.2.5.3	Test Procedure	252
8.2.5.4	Test Conditions and Reports	252
8.2.6	Torsion Test	253
8.2.6.1	Purpose	253
8.2.6.2	Testing Device	253
8.2.6.3	Test Procedure	253
8.2.6.4	Test Conditions and Reporting	254
8.2.7	Tensile Test	255
8.2.7.1	Purpose	255
8.2.7.2	Testing Device	255
8.2.7.3	Test Procedure	255
8.2.7.4	Test Conditions and Reports	256
8.3	Environmental Test Methods	256
8.3.1	Storage at High Temperature	257
8.3.1.1	Purpose	257
8.3.1.2	Test Conditions	257
8.3.2	Storage at Low Temperature	257
8.3.2.1	Purpose	257
8.3.2.2	Test Conditions	257
8.3.3	Temperature Change and Storage	257
8.3.3.1	Purpose	257
8.3.3.2	Rapid Temperature Change	258
8.3.3.3	Specified Rate of Temperature Change	258
8.3.4	Humidity and Heat, Steady State, and Storage	258
8.3.4.1	Purpose	258
8.3.4.2	Test Conditions	258
8.3.5	Moist Heat, Circulation, and Storage	259
8.3.5.1	Purpose	259
8.3.5.2	Test Conditions	259
8.3.6	High-Temperature Operation	260
8.3.6.1	Purpose	260
8.3.6.2	Test Conditions	260
8.3.7	Low-Temperature Operation	260
8.3.7.1	Purpose	260
8.3.7.2	Test Conditions	260
8.3.8	Humidity and Heat, Steady State, Operation	261
8.3.8.1	Purpose	261
8.3.8.2	Test Conditions	261
8.4	Mechanical Test Methods (Impact and Hardness Tests)	261
8.4.1	Scope	261
8.4.2	Sample Preparation	261
8.4.3	Ball Drop Test	262

8.4.3.1	Purpose	262
8.4.3.2	Testing Device	262
8.4.3.3	Test Procedure	263
8.4.4	Impact Test	263
8.4.4.1	Purpose	263
8.4.4.2	Test Equipment for Impact Testing	263
8.4.4.3	Test Process	264
8.4.5	Pendulum Side Impact Test	265
8.4.5.1	Purpose	265
8.4.5.2	Testing Device	265
8.4.5.3	Test Steps	266
8.4.6	Stylus Scratch Test	266
8.4.6.1	Purpose	266
8.4.6.2	Testing Device	266
8.4.6.3	Test Steps	267
8.4.7	Steel Wool Wear Test	267
8.4.7.1	Purpose	267
8.4.7.2	Testing Device	268
8.4.7.3	Test Procedure	268
	References	268
9	Analysis of Flexible Electronic Packaging Enterprise	271
	<i>Zhenrong Wei</i>	
9.1	Flexible Electronic Packaging Enterprise	271
9.1.1	Samsung SDI-Korea	271
9.1.1.1	Product Appearance	271
9.1.1.2	Business History	271
9.1.1.3	Product Features	272
9.1.1.4	Product Specifications	272
9.1.2	LG Chem-Korea	274
9.1.2.1	Basic Materials and Chemicals	274
9.1.2.2	Information Technology and Electronic Materials	274
9.1.2.3	Energy Solutions	275
9.1.3	3M-United States	279
9.1.4	UDC-United States	284
9.1.5	Amcor-United States	286
9.1.6	Vitriflex-United States	289
9.1.7	TBF-Singapore	291
9.1.8	Fraunhofer ISC-Germany	295
9.1.9	Sigma Technologies-The United States	298
9.1.9.1	Monolayer Barrier Films	298
9.1.9.2	Multilayer Barrier Films	298
9.1.10	Toppan Printing-Japan	300
9.1.10.1	Information Network	300
9.1.10.2	Living Environment	301

9.1.10.3	Electronics	301
9.1.11	BASF(Rolic)-Germany	305
9.1.12	Vitex(Samsung)-The United States	308
9.1.13	General Electrics-The United States	316
9.1.14	Mitsui Chem-Japan	318
9.1.15	Mitsubishi Chem-Japan	320
9.1.16	Fujifilm-Japan	321
9.1.17	Konica Minolta-Japan	324
9.1.18	KDX-China	325
9.1.19	Wanshun-China	327
9.1.20	Lucky-China	329
9.2	Analysis of Flexible Electronic Packaging Enterprises	331
	References	334
10	Flexible Electronics Packaging Development Trends	337
	<i>Mingqiang Liu</i>	
10.1	Flexible Electronics Packaging Trends Overview	337
10.2	Introduction of Three Packaging Technologies for Flexible Electronic Devices	341
10.2.1	Application of Electronic Packaging Technology in the OLED Field	341
10.2.2	Advances in Packaging Research for Flexible Bioelectronic Implants	345
10.2.3	Advances in Packaging Research of Flexible Chalcogenide and Organic Photovoltaics	348
10.3	Flexible Electronics Packaging Development Trend Summary	351
	References	351
	Index	353

